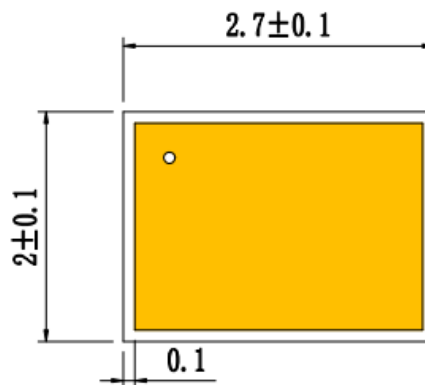
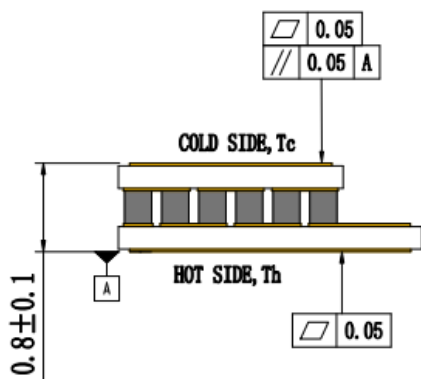
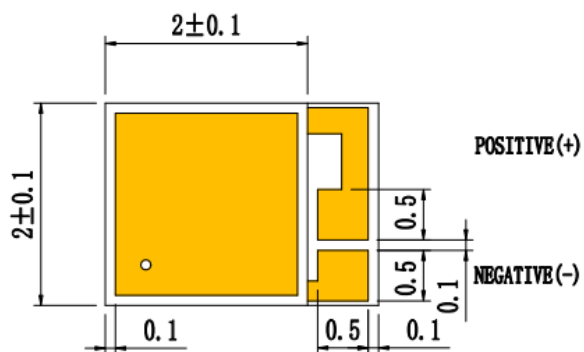
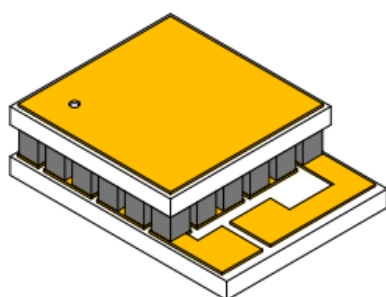


**Product Code: TEM1-01801B**

**1. 组件尺寸(mm) Module Dimensions**



## 2. 电参数 Electrical Parameters

性能参数								
Th=27℃				Th=75℃				Ta=27℃
$\Delta T_{max}/℃$	Qc max/W	Umax/V	I <sub>max</sub> /A	$\Delta T_{max}/℃$	Qc max/W	Umax/V	I <sub>max</sub> /A	ACR/Ω
70.3	1.25	2.16	1.00	89.3	1.54	2.51	0.92	1.91±10%

## 3. 标注信息 Graphic Notes

- 半导体材料: 碲化铋  $\text{Bi}_2\text{Te}_3$  alloy , 18 P, N Couples
- Thermoelectric material: Bismuth Telluride, 18 P, N Couples
- 陶瓷基板: AlN 白色  
Ceramic plate: AlN white color
- 金属化层组成: Cu/Ni/Pd/Au, 厚度:  $\geq 20\mu\text{m}/3-6\mu\text{m}/0.075\mu\text{m}/0.1-0.15\mu\text{m}$
- Metallic layers: Cu/Ni/Pd/Au, Thickness:  $\geq 20\mu\text{m}/3-6\mu\text{m}/0.075\mu\text{m}/0.1-0.15\mu\text{m}$
- 内部焊料组成: AuSn; 最高允许工艺温度 265 摄氏度, 2 分钟  
Interior solder composition: AuSn, Max. process temperature 265 Celsius Degree for 2 min.